



Diode Modules MDx110



AS ENERGI

$I_{F(AV)}$ 110A
 V_{RRM} 1900~2500V
 I_{FSM} 2.60 A $\times 10^3$
 I^2t 33 A 2 S $\times 10^3$

Features:

- Isolated mounting base 3000V~
- Pressure contact technology with increased power cycling capability
- Space and weight savings

Typical Applications

- AC/DC Motor drives
- Various rectifiers
- DC supply for PWM inverter

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T_j (°C)	VALUE			UNIT
				Min	Type	Max	
$I_{F(AV)}$	Mean forward current	180° half sine wave 50Hz Single side cooled, $T_c=100^\circ C$	150			110	A
$I_{F(RMS)}$	RMS forward current		150			173	A
V_{RRM}	Repetitive peak reverse voltage	V_{RRM} tp=10ms $V_{RsM}=V_{RRM}+100V$	150	1900		2500	V
I_{RRM}	Repetitive peak current	at V_{RRM}	150			12	mA
I_{FSM}	Surge forward current	10ms half sine wave	150			2.60	KA
I^2t	I^2T for fusing coordination	$V_R=0.6V_{RRM}$				33	A 2 s $\times 10^3$
V_{FO}	Threshold voltage		150			0.85	V
r_F	Forward slop resistance					1.88	mΩ
V_{FM}	Peak forward voltage	$I_{FM}=330A$	25			1.55	V
$R_{th(j-c)}$	Thermal resistance Junction to case	At 180° sine Single side cooled				0.33	°C /W
$R_{th(c-h)}$	Thermal resistance case to heatsink	At 180° sine Single side cooled				0.20	°C /W
V_{iso}	Isolation voltage	50Hz,R.M.S,t=1min, $I_{iso}=1mA$ (max)	3000				V
F_m	Terminal connection torque(M5)				4		N·m
	Mounting torque(M6)				6		N·m
T_{stg}	Stored temperature			-40		125	°C
W_t	Weight				170		g
Outline							

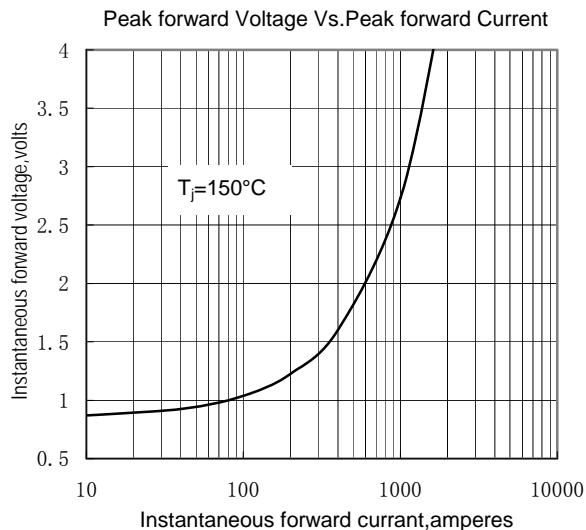


Fig.1

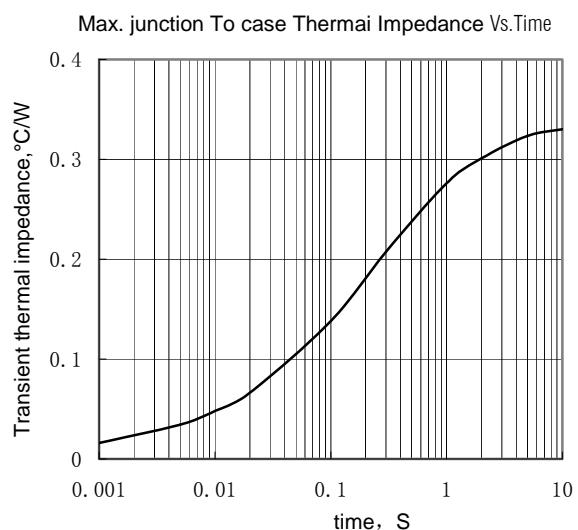


Fig.2

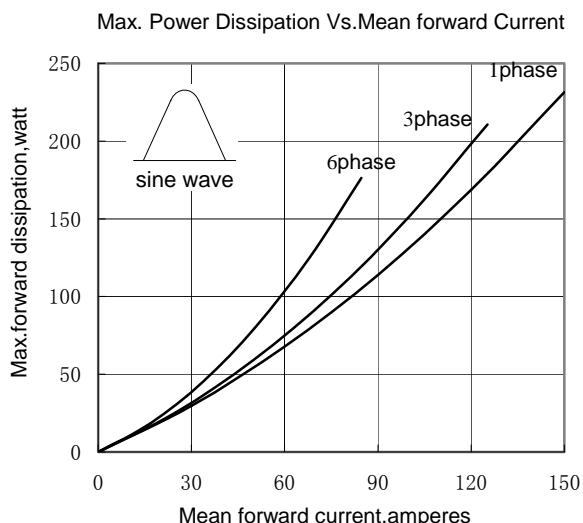


Fig.3

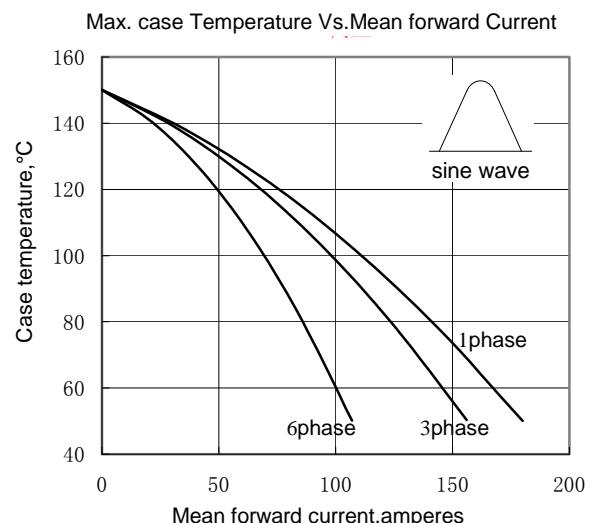


Fig.4

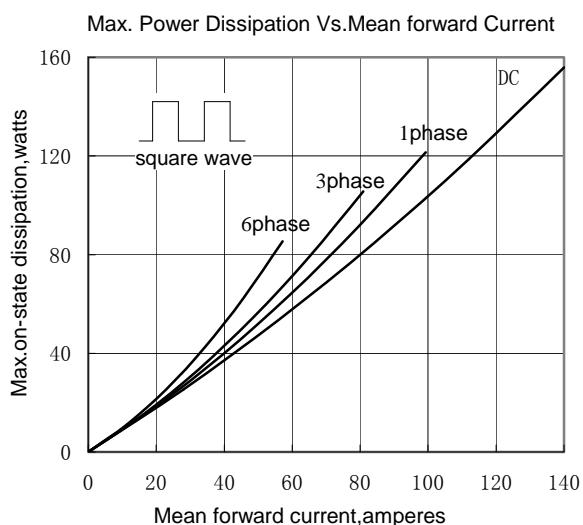


Fig.5

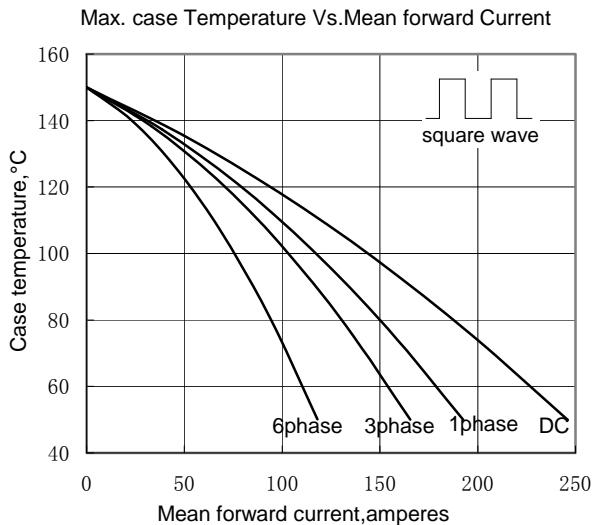


Fig.6

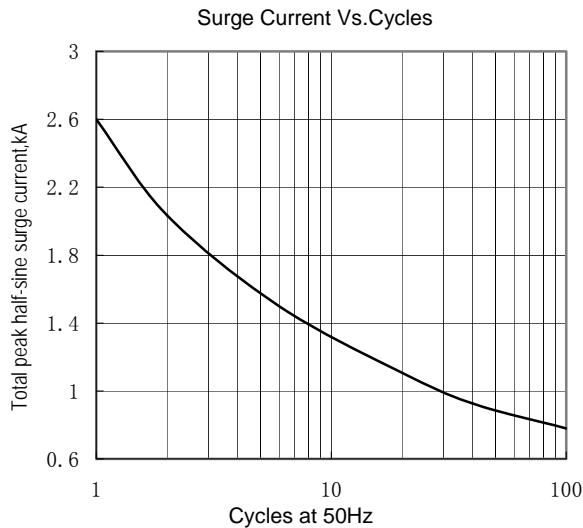


Fig.7

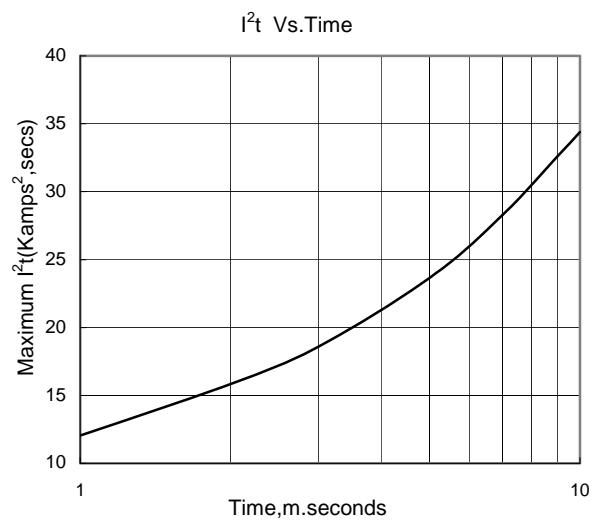


Fig.8

Outline:

